

Taiwan Semiconductor

Glass Passivated Bridge Rectifiers

FEATURES

- Glass passivated junction
- Ideal for printed circuit board
- High case dielectric strength
- Typical IR less than 0.1µA
- High surge current capability
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC







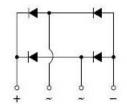
KBU

MECHANICAL DATA

Case: KBU

Molding compound, UL flammability classification rating 94V-0 **Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test **Mounting torque:** 0.56 N·m max. **Weight:** 7.2 g (approximately)



PARAMETER	SYMBOL	KBU	KBU	KBU	KBU	KBU	KBU	KBU	Unit
	01111202	1001G	1002G	1003G	1004G	1005G	1006G	1007G	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	٧
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	٧
Maximum average forward rectified current	I _{F(AV)}				10				Α
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}				200				Α
Rating for fusing (t<8.3ms)	l ² t				166				A^2s
Maximum instantaneous forward voltage (Note 1) $I_{\text{F}}\!=5~\text{A}$ $I_{\text{F}}\!=10~\text{A}$	V _F				1.0 1.1				٧
Maximum DC reverse current $T_J=25$ °C at rated DC blocking voltage $T_J=125$ °C	I _R	5 500			μΑ				
Typical junction capacitance per leg	Cj				400				pF
Typical thermal resistance	$R_{ heta JC} \ R_{ heta JA}$	2.2 25			°C/W				
Operating junction temperature range	TJ			-	55 to +15	50			οС
Storage temperature range	T _{STG}			-	55 to +15	50			οС

Note 1: Pulse Test with PW=300µs, 1% Duty Cycle

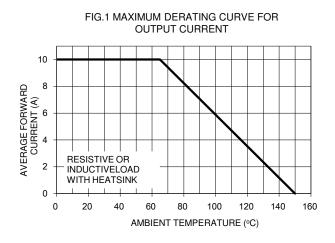
Note 2: Measured at 1MHz and applied Reverse Voltage of 4.0V D.C.

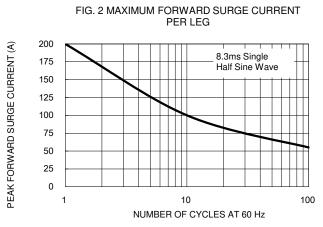


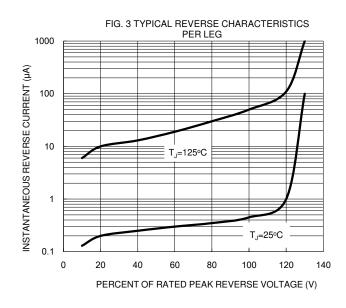
ORDERING INFORMATION								
ORDERING CODE	PACKAGE	PACKING						
KBU1001G T0	KBU	500 / Trays						
KBU1002G T0	KBU	500 / Trays						
KBU1003G T0	KBU	500 / Trays						
KBU1004G T0	KBU	500 / Trays						
KBU1005G T0	KBU	500 / Trays						
KBU1006G T0	KBU	500 / Trays						
KBU1007G T0	KBU	500 / Trays						

RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)







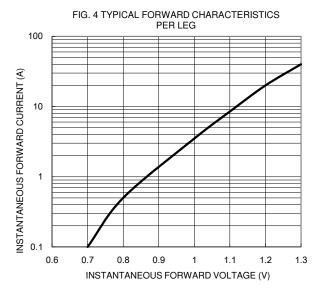
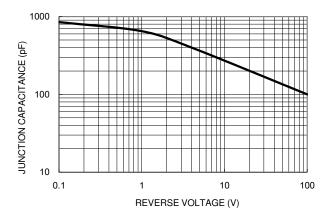


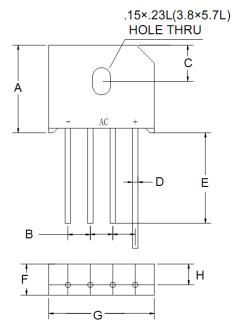


FIG. 5 TYPICAL JUNCTION CAPACITANCE



PACKAGE OUTLINE DIMENSIONS

KBU



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	18.8	19.8	0.740	0.780	
В	4.6	5.6	0.181	0.220	
С	8.2 (TYP.)		0.322 (TYP.)		
D	1.2	1.3	0.047	0.051	
Е	20.0	-	0.787	-	
F	6.8	7.1	0.268	0.280	
G	22.7	23.7	0.894	0.933	
Н	4.6	5.0	0.181	0.197	

MARKING DIAGRAM



P/N = Specific Device Code

= Date Code YWW

F = Factory Code



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